

W138A8QMP/ID/TG

HIGH EFFICIENCY RED

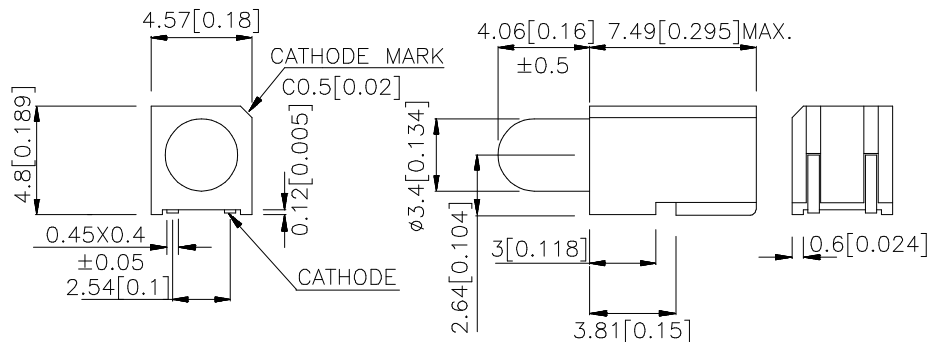
Features

- PRE-TRIMMED LEADS FOR PC MOUNTING.
- CAN BE ASSEMBLED WITH EACH OTHER.
- I.C. COMPATIBLE.
- BLACK CASE ENHANCES CONTRAST RATIO.
- WIDE VIEWING ANGLE.
- HIGH RELIABILITY LIFE MEASURED IN YEARS.
- HOUSING MATERIAL: PPA
- HIGH GLASS TRANSFER TEMPERATURE EPOXY.
- SOFTER & THINNER LEAD FRAMES.
- PACKAGE : 1000PCS / REEL.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 10 mA		Viewing Angle
			Min.	Typ.	θ1/2
W138A8QMP/ID/TG	HIGH EFFICIENCY RED(GaAsP/GaP)	RED DIFFUSED	12	20	60°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

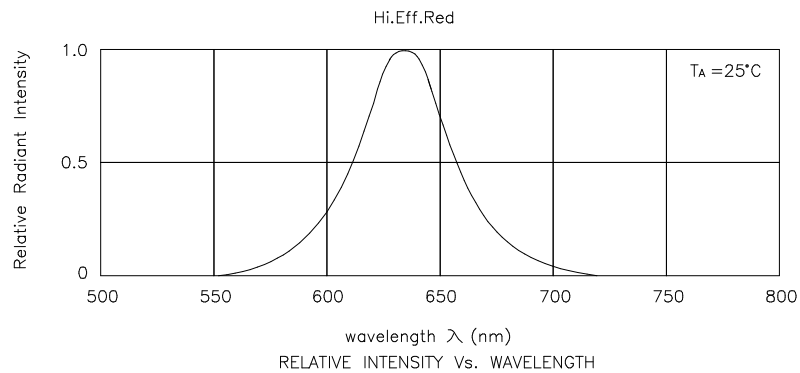
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	High Efficiency Red	627		nm	I _F =20mA
λ _D	Dominate Wavelength	High Efficiency Red	625		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	High Efficiency Red	45		nm	I _F =20mA
C	Capacitance	High Efficiency Red	15		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	High Efficiency Red	2.0	2.5	V	I _F =20mA
I _R	Reverse Current	High Efficiency Red		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	High Efficiency Red	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	160	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

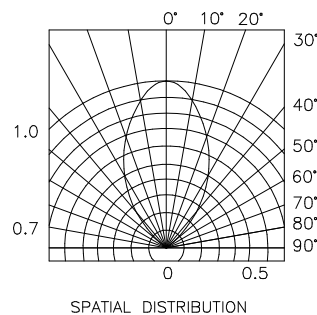
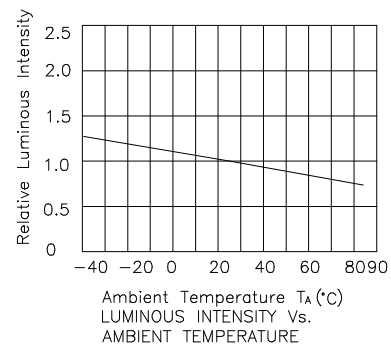
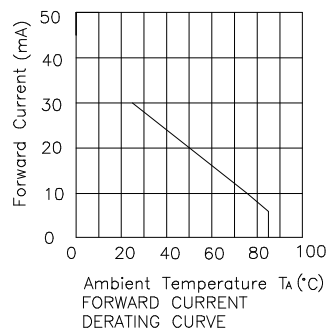
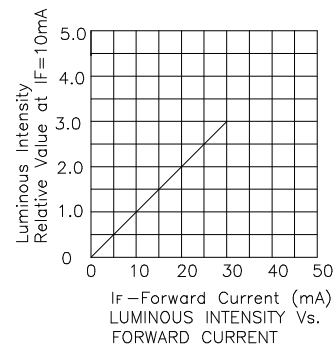
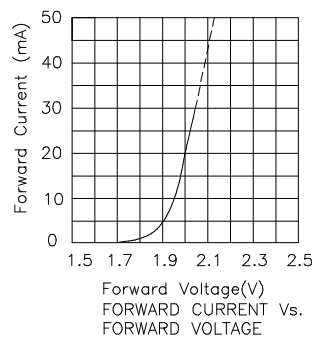
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



High Efficiency Red

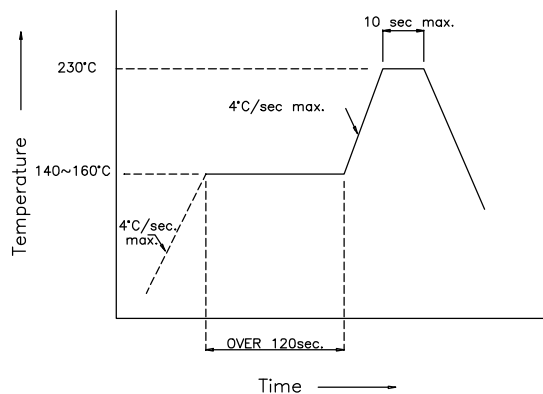
W138A8QMP/ID/TG



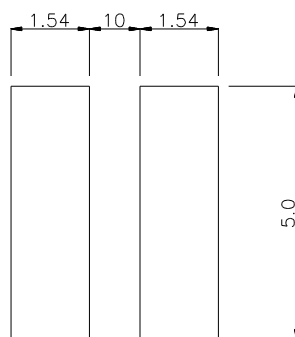
W138A8QMP/ID/TG

SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process."



Recommended Soldering Pattern



Tape Specifications

